

DATA IMAGE CORPORATION

LCD Module Specification

ITEM NO.: **CM160230SFAYBGI1**

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Customer Companies	R&D Dept.	Q.C. Dept.	Eng. Dept.	Prod. Dept.
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Approved by	Version:	Issued Date:	Sheet Code:	Total Pages:
	А	2006/3/17		26



2. RECORD OF REVISION

Rev	Date	Item	Page	Comment
Α	06/3/17			New Release

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CM160230SFAYBGI1 REV:A

3. GENERAL SPECIFICATION

Display Format :	To characters (VV) × 2	z iines (H)
Character Size :	4.07 (\	W) ×	7.76 (H) mm
View Area :	80 (\	W) ×	20.4 (H) mm
General Dimensions :	100 (\	W) ×	38.8 (H	$) \times 13.3$ (T) mm Max.
Weight:	48 g max.			
LCD Type & Background Color :	STN Blue Gray	V STN Yello	l w Green	FSTN
Polarizer mode :	Reflective	V Tran	sflective	
	Transmissive	Neg	ative	
View Angle :	V 6 O'clock	12 C)'clock	Others
Backlight :	VLED	EL		CCFL
Backlight Color :	V Yellow green	Amb	per	Blue Green
	White	Othe	ers	
Controller / Driver :	ST7066U0A			
Temperature Range :	Normal Operating 0 t Storage -20	to 50°C 0 to 70°C	Ope	e Temperature rating -20 to 70°C age -30 to 80°C
Pixel Color : Blue				
REMARK:				
Our components and	I processes are co	mpliant to	o RoHS s	standard.



DATA 1MAGE 4. ABSOLUTE MAXIMUM RATINGS

4.1 ELECTRICAL ABSOLUTE MAXIMUM RATINGS

Vss=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage (Logic)	VDD-VSS	-0.3	7	V
Supply Voltage (LCD Driver)	VDD-Vo	-0.3	10	V
Input Voltage	VI	-0.3	VDD+0.3	V
Operating Temperature	TOP	-20	70	°C
Storage Temperature	TSTG	-30	80	°C

4.2 ENVIRONMENTAL ABSOLUTE MAXIMUM RATINGS

Item	Operating		Sto	rage	Comment	
	(Min.)	Max.)	(Min.)	(Max.)	Comment	
Ambient Temp	-20	70	-30 80		Note (1)	
Humidity	Note (2)		Note(2)		Without Condensation	
Vibration		4.9M/S ²		19.6M/S ²	XYZ Direction	
Shock		29.4M/S ²		490M/S ²	XYZ Direction	

Note(1) Ta = 0° C : 50Hr Max. Note(2) Ta ≤ 40 °C: 90% RH Max.

Ta $\geq 40^{\circ}\text{C}$: Absolute humidity must be lower than the humidity

of 90% RH at 40°C.

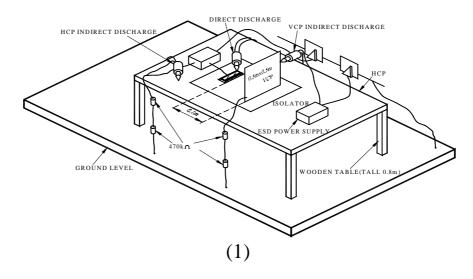


4. 3 Electronic Static Discharge maximum rating

ESD test method: IEC1000-4-2

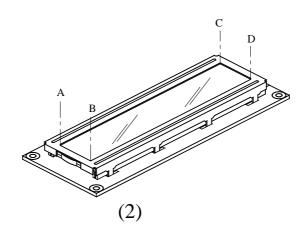
Item	Description					
Testing environment	Ambient temp	Ambient temperature :15°C to 35 °C				
	Humidity: 30%	Humidity: 30% to 60 %				
	LCM (E.U.T)	: Power up				
Testing equipment	Manufacture: 1	Noise Ken, Model No. ESD-100L				
Testing condition	See drawing 1					
Direct discharge	$0 \text{ to } \pm 6 \text{ KV}$	Discharge point, see drawing 2				
Indirect discharge	$0 \text{ to } \pm 12\text{KV}$	Discharge point, see drawing 1				
Pass condition	No malfunctio	n of unit. Temporary malfunction of unit which				
	can be recovered by system reset					
Fail condition	Non. Recovera	able malfunction of LCM or system				

FIG 1 ESD TESTING EQUIPMENT



DIRECT CONTACT DISCHARGE

CONTACT POINT: A.B.C.D





ELECTRI CAL CHARACTERI STI CS

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage (Logic)	VDD-VSS		2.7	5.0	5.5	V
0 1 1/ //		-20°C	4.1	4.4	4.7	
Supply Voltage (LCD)	VDD-VO	25°C	3.8	4.1	4.3	V
		70°C	3.5	3.8	4.0	
Input Voltage	VIH		0.7*VDD		Vdd	V
Input Voltage	VIL		-0.3		0.6	V
Logic Supply	IDD	VDD-VSS=5V		1.38		mA
Current	IEE	V כ=887-טט		0.5		mA

6. ELECTRO-OPTI CAL CHARACTERI STI CS

ITEM	Symbol	Condition	Min.	Тур.	Max.	Unit	Ref.
Diag Time	Т,	-20°C			10000		
Rise Time	Tr	25°C			250	ms	Note (1)
Fall Time	Tf	-20°C			10000	ms	Note (1)
raii Tiille	11	25°C			250	1115	
Contrast	CR	25°C	4				Note (3)
View Angle	θ1~θ2	25°C &	-20		35		Note (2)
view Arigie	∅1, ∅ 2	CR≥3	-30	-	30		Note (2)
Frame Frequency	Ff	25°C	32	64	200	Hz	

Note (1) & (2) : See next page

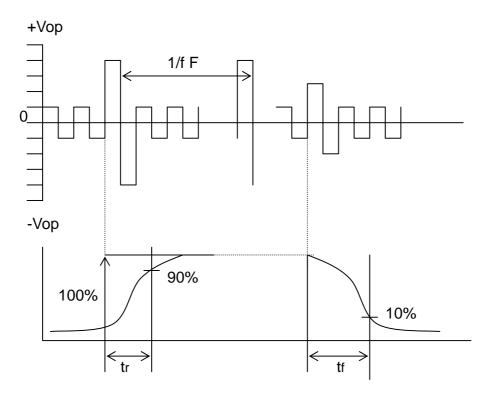
Note (3): Contrast ration is defined under the following condition:

CR= Brightness of non-selected condition Brightness of selected condition

- (a). Temperature ----- 25°C
- (b). Frame frequency ---- 64Hz
- (c). Viewing angle ----- $\theta = 0^{\circ}$, $\emptyset = 0^{\circ}$
- (d). Operating voltage --- 4.1V



Note (1) Response time is measured as the shortest period of time possible between the change in state of an LCD segment as demonstrated below:

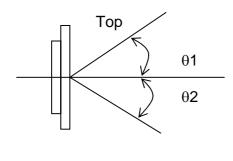


Condition:

- (a). Temperature -----25°C
- (b). Frame frequency ----- 64Hz
- (c). View Angle ----- $\theta = 0^{\circ}$, $\varnothing = 0^{\circ}$
- (d). Operating voltage ----- 4.1V

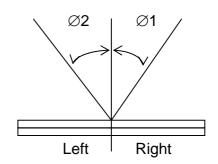
Note (2) Definition of View Angle

Top – Bottom direction



Bottom

Right -- Left direction



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6.1 LED ELECTRO-OPTICAL CHARACTERISTIC

Ta = 25°C

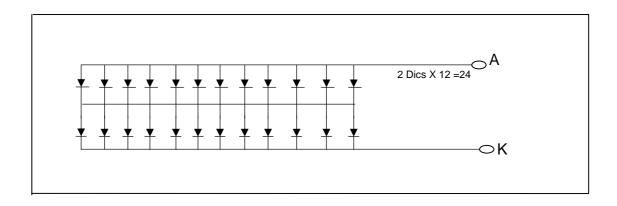
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF = 120mA Yellow Green		4.1	4.3	V
Luminous Intensity	Iv	IF = 120mA Yellow Green	140	200		cd/m ²
Peak Emission	λΡ	IF = 120mA Yellow Green		568		nm
Spectrum Radiation	Δλ	IF = 120mA Yellow Green		30		nm
Reverse Current	IR	VR = 8V Yellow Green			0.2	mA

Note: Measured at the bared LED backlight unit.

6.2 LED MAXIMUM OPERATING RANGE

Item	Symbol	Yellow Green	Unit
Power Dissipation	Pad	0.774	W
Forward Current	IAF	180	mA
Reverse Voltage	VR	8	V

6.2.1 LED ARRAY BLOCK DIAGRAM





7. TIMING CHARACTERISTICS

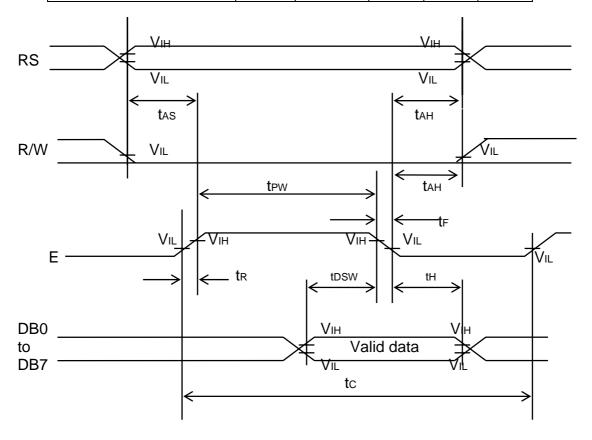
7.1 WRITE TIMING

AC characteristics (VDD=5V,Ta=25°C)

Item	Symbol	Condition	Min.	Max.	Unit
E cycle time	tc		1200		
E pulse width	tPW		140		
E rise/fall time	tR, tF			25	
RS and RW, E Address Setup time	tAS	VDD = 5V	0		ns
RW and RS ,E Address Hold time	tAH		10		
Data setup time	tDSW		40		
Data hold time	tH		10		

AC characteristics (VDD=2.7V,Ta=25°C)

Item	Symbol	Condition	Min.	Max.	Unit
E cycle time	tc		1200		
E pulse width	tPW		460		
E rise/fall time	tR, tF			25	
RS and RW, E Address Setup time	tAS	VDD = 2.7V	0		ns
RW and RS ,E Address Hold time	tAH]	10		
Data setup time	tDSW		80		
Data hold time	tH		10		





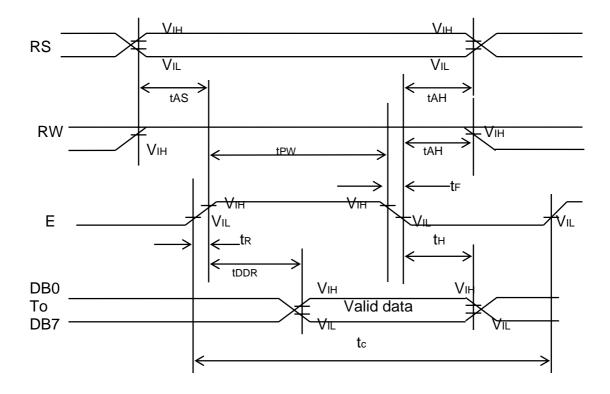
7.2 READ TIMING

AC chaVracteristics (VDD=5V,Ta=25°C)

Item	Symbol	Condition	Min.	Max.	Unit
E cycle time	tc		1200	1	
E pulse width	tPW		140		
E rise/fall time	tR, tF			25	
RS and RW, E Address Setup time	tAS	VDD = 5V	0		nc
RS and RW ,E Address Hold time	tAH		10		ns
Data Setup time	tDDR]		100	
Data hold time	tH		10		

AC characteristics (VDD=2.7V,Ta=25°C)

Item	Symbol	Condition	Min.	Max.	Unit		
E cycle time	tc		1200				
E pulse width (high level)	tPW		480				
E rise/fall time	tR, tF			25			
RW and RS ,E Address setup time	tAS	VDD = 2.7V	0		ns		
RW and RS ,E Address Hold time	tAH		10				
Data output delay time	tDDR			320			
Data hold time	tH		10				

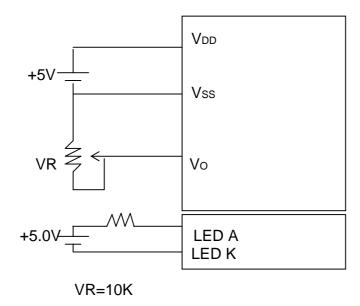




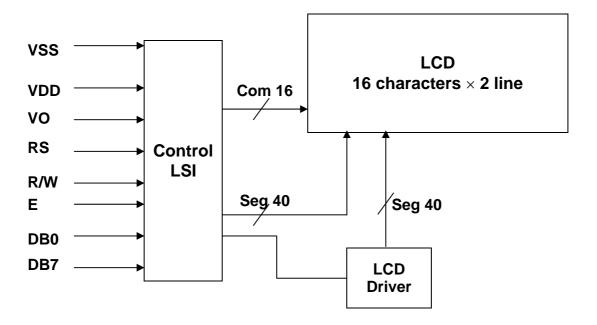
8. PIN CONNECTIONS

No.	Symbol	Function
1	VSS	Ground, 0V
2	VDD	Logic power supply, +5V
3	VO	Voltage for LCD drive
4	RS	Data / Instruction register select
5	R/W	Read / Write
6	E	Enable signal, start data read/write
7	DB0	
8	DB1	
9	DB2	
10	DB3	Data Bus Line
11	DB4	
12	DB5	
13	DB6	
14	DB7	
15	LED K	LED Cathode, ground 0V
16	LED A	LED Anode, power supply +

9. POWER SUPPLY









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10.1 INSTRUCTIONS

				ND.								
Instruction		ı	ı	Instr	ucti	on C	ode)	ı	ı	DESCRIPTION	Executed Time(fosc
	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0		=270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM and set DDRAM address to "00H " from AC	1.52mS
Cursor At Home	0	0	0	0	0	0	0	0	1	-	Set DDRAM address to "00H" from AC and return cursor to its original Position if shifted. The contents of DDRAM are not changed.	1.52mS
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	37μS
Display On/Off Control	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor(C), and Blinking of cursor(B) ON/OFF control bit.	37μS
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	-	-	Set cursor moving and display shifts cursor bit, and the direction, without changing of DDRAM data.	37μS
Function Set	0	0	0	0	1	DL	N	F	-	-	Sets interface data length (DL:8-BIT/4-BIT), number of display lines(N:2-line/1-line) and, display font type (F:5x11dots/5x8 dots).	37μS
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	37μS
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	37μS
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μS
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM / CGRAM)	43μS
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Reads data from internal RAM (DDRAM / CGRAM).	43μS

^{*&}quot;-":don't care

NOTE: When an MPU program with checking the Busy Flag(DB7) is made, it must be necessary 1/2Fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag(DB7)goes to "LOW".



10.2 8-Bit Operation,8-Digit×2-Line Display Example

Step					Instru	ıction						
No	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
1		-	pply o	-		initia	lized	by th	e			Initialized. No display.
2	Fun 0	ction 0	set 0	0	1	1	1	0	*	*		Sets to 8-bit operation and selects 2-line display and 5×8 dot character font.
3	Disp	olay o	n/off o	contro	ol		Turns on display and cursor.					
	0	0	0	0	0	0	1	1	1	0		All display is in space mode because of initialization.
4	Ent	ry mo	de set									Sets mode to increment the address by one and to shift the
	0	0	0	0	0	0	0	1	1	0		cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.
5	Wri	te dat	a to C	CGRA	M/DI	ORAN	1				H_	Writes H. DDRAM has already been selected by initialization
	1	0	0	1	0	0	1	0	0	0		when the power was turned on. The cursor is incremented by one and shifted to the right
6						•						
7	Wri	te dat	a to C	GRA	M/DI	ORAN	1				НІТАСНІ	Writes I.
	1	0	0	1	0	0	1	0	0	1	_	
8	Set 1	DDRA	M ad	ldress	5						НІТАСНІ	Sets DDRAM address so that The cursor is positioned at the
	0	0	1	1	0	0	0	0	0	0		Head of the second line.
9	Wri	te dat	a to C	CGRA	M/DI	ORAN	1				НІТАСНІ	Writes M.
	1	0	0	1	0	0	1	1	0	1	<u>M_</u>	
10						•						
11	Wri	te dat	a to C	CGRA	M/DI	ORAN	1				НІТАСНІ	Writes O.
	1	0	0	1	0	0	1	1	1	1	MICROCO_	
12		•	de set								НІТАСНІ	Sets mode to shift display at the time of write.
			0			0	0	1	1	1	MICROCO_	
13	Wri 1	te dat 0	a to C	CGRA 1	.M/DI 0	ORAN 0	1	1	0	1	ITACHI ICROCOM_	Writes M. Display is shifted to the left. The first and second lines both shift at the same time.
14											; ;	
15	Retu	urn ho	ome			-					<u>H</u> ITACHI	Returns both display and
	0	0	0	0	0	0	0	0	1	0	MICROCOM	cursor to the original position (address 0).

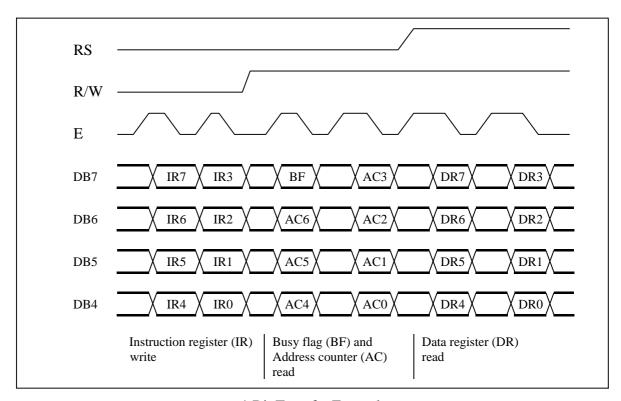


10.3 Interfacing to the MPU

The IC can send data in either two 4-bit operations, thus allowing interfacing with 4-or 8-bit MPUs.

• For 4-bit interface data, only four bus lines (DB4 to DB7) are used for transfer. Bus lines DB0 to DB3 are disabled. The data transfer between the IC and the MPU is completed after the 4-bit data has been transferred twice. As for the order of data transfer, the four high order bits (for 8-bit operation, DB4 to DB7) are transferred before the four low order bits (for 8-bit operation, DB0 to DB3).

The busy flag must be checked (one instruction) after the 4-bit data has been transferred twice. Two more 4-bit operations then transfer the busy flag and address counter data.



4-Bit Transfer Example

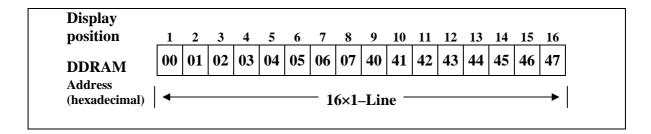
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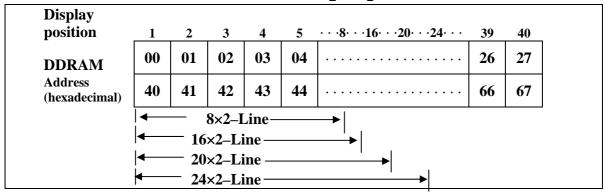


10.4

1-Line Display



2-Line Display



4-Line Display

Display						
position	1	2	3		15	16
DDRAM	00	01	02		0E	0F
Address (hexadecimal)	40	41	42		4 E	4 F
	14	15	16		1E	1F
	54	55	56		5E	5 F
	<u> </u>			16×4 Line		

00				19	20
00	01	02		12	13
40	41	42		52	53
14	15	16		26	27
54	55	56		66	67
	14	14 15	14 15 16	14 15 16	14 15 16 26



10.5 CGRAM

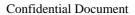
Relationship between CGRAM Addresses, Character Codes (DDRAM) and Patterns (CGRAM Data)

For 5×8 dot character patterns

Character Codes (DDRAM data)	CGRAM	I Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3	2 1 0	7 6 5 4 3 2 1 0	
High Low	High	Low	High Low	
0 0 0 0 * 0 0 0	0 0 0	0 0 0 0 0 0 0 1 0 1 0 0 1 1 1 1 0 0 1 1 1 1 1 1 0 0	* * * * 1 1 1 1 0 1 0 0 0 1 1 0 0 0 1 1 1 1 1 0 1 0 1 0	Character Pattern (1)
		1 1 1	* * * 0 0 0 0 0	} Cursor position
0 0 0 0 * 0 0 1	0 0 1	1 0 0 1 0 1 1 1 0 1 1 1	* * * 1 0 0 0 1 0 1 0 1 0 1 0 1 0 1 0 0 1 0 0 1 0 0 0 1 0	Character Pattern (2)
		$\begin{bmatrix} 0 & 0 & 0 \\ 0 & 0 & 1 \end{bmatrix}$	* * *	
Г	I	: .	· · ! !	I
0 0 0 0 * 1 1 1	1 1 1	1 0 0 1 0 1 1 1 0 1 1 1	* * *	

Notes: 1. Character code bits 0 to 2 correspond to CGRAM address bits 3 to 5 (3 bits: 8 types).

- 2. CGRAM address bits 0 to 2 designate the character pattern line position. The 8th line is the cursor position and its display is formed by a logical OR with the cursor. Maintain the 8th line data, corresponding to the cursor display position, at 0 as the cursor display.
 - If the 8th line data is 1, 1 bits will light up the 8th line regardless of the cursor presence.
- 3. Character pattern row positions correspond to CGRAM data bits 0 to 4 (bit 4 being at the left).
- 4. As shown Table 5, CGRAM character patterns are selected when character code bits 4 to 7 are all 0. However, since character code bit 3 has no effect, the R display example above can be selected by either character code 00H or 08H.
- 5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.
- * Indicates no effect.





10.6 Correspondence between Character Codes and Character Patterns (ROM Code:)

NO.7	066-	0A	20 100	20									(elo_	53		
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)							***				3	**	**	**	:
0001	(2)			****			***	***			8		***		***	
0010	(3)		**									*		*	***	
0011	(4)							**			*			*****		**
0100	(5)		**	***			Ċ.	***				I.	k	**	J.	
0101	(6)		***				***	S			*	Ä	***		***	ij,
0110	7)			* * *			***	**			***		***	****		2
0111	(8)							*			*.		**	****	***	31
1000	(1)		×								*		**			X
1001	(2)				*		••••				÷	Ť		**	**	
1010	(3)		*	**	*		***	!				***	***			***
1011	(4)		*	***	×	****					×	**			*	3.7
1100	(5)		*			**	*	****			17	. ;	****	***		pa;
1101	(6)		*	**		***	**					X	**,	**	**	**
1110	7)		**	*				₹*			3	***			M	
1111	(8)			**		****	***	*			***	•	7	**		



QUALITY ASSURANCE

11.1 Test Condition

11.1.1 Temperature and Humidity(Ambient Temperature)

Temperature : $20 \pm 5^{\circ}$ C Humidity : $65 \pm 5\%$

11.1.2 Operation

Unless specified otherwise, test will be conducted under function state.

11.1.3 Container

Unless specified otherwise, vibration test will be conducted to the product itself without putting it in a container.

11.1.4 Test Frequency

In case of related to deterioration such as shock test. It will be conducted only once.

11.1.5 Test Method

No.	Parameter	Conditions	Regulations
1	High Temperature Operating	70 ± 2 °C	Note 3
2	Low Temperature Operating	-20 ± 2 °C	Note 3
3	High Temperature Storage	80 ± 2 °C	Note 3
4	Low Temperature Storage	-30 ± 2 °C	Note 3
5	Vibration Test (Non-operation state)	Total fixed amplitude: 1.5mm Vibration Frequency: 10 ~ 55Hz One cycle 60 seconds to 3 directions of X.Y.Z. for each 15 minutes	Note 3
6	Damp Proof Test (Non-operation state)	40°C ± 2°C, 90~95%RH, 96h	Note 1,2
7	Shock Test (Non-operation state)	To be measured after dropping from 60cm high once concrete surface in packing state	Note 3

Note 1: Returned under normal temperature and humidity for 4 hrs.

Note 2: No dew condensation to be observed.

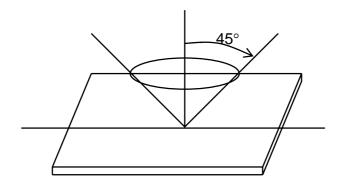
Note 3: No change on display and in operation under the test condition



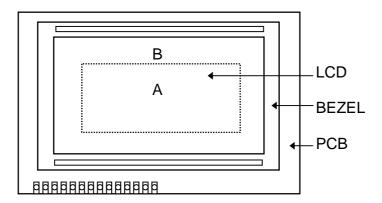
11.2 Inspection condition

11.2.1 Inspection conditions

The LCD shall be inspected under 40W white fluorescent light.



11.2.2 Definition of applicable Zones



A: Display Area B: Non-Display Area

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11.2.3 Inspection Parameters

No.	Parameter	Criteria	
INO.	Parameter	Criteria	
1	Black or White spots	Dimension A B D D < 0.15 * *	Class Of AQL Defects Level
		$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Minor 2.5 t) / 2 * : Disregard
2	Scratch, Substances		Class Of AQL Defects Level
		2.0 ≥ L 0.08 ≥ W 2 3 — 0.1 < W	Minor 2.5 sregard odule
3	Air Bubbles (between glass & polarizer)		
		Zone Acceptable number Dimension A B	Class of AQL Defects
		$\begin{array}{c ccccc} D \le 0.15 & * & * \\ \hline 0.15 < D \le 0.25 & 2 & * \\ \hline 0.25 < D & 0 & 1 \\ \hline * : Disregard \\ Total defects shall not excess 3/r \\ \hline \end{array}$	Minor 2.5 module.
4	Uniformity of Pixel	(1) Pixel shape (with Dent) 0.	152



	IMAGE		Confidential Document
	4 Uniformity of Pixel		(2) Pixel shape (with Projection)
			Should not be connected to next pixel
			(3) Pin hole
4			X Y
			(4) Deformation
			Total acceptable number : 1/pixel, 5/cell
Class of defects	Major		Definition
		AQL 0.65%	It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.
		AQL 1.00%	It is a defect that is likely to assembly size and not result in functioning problem.
	Minor	AQL 2.5%	It is a defect that will not result in functioning problem with deviation classified.

11.3 Sampling Condition

Unless otherwise agree in written, the sampling inspection shall be applied to the incoming inspection of customer. Lot size: Quantity of shipment lot per model.

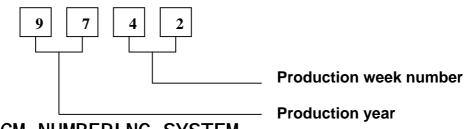
Sampling type: normal inspection, single sampling

Sampling table: MIL-STD-105E

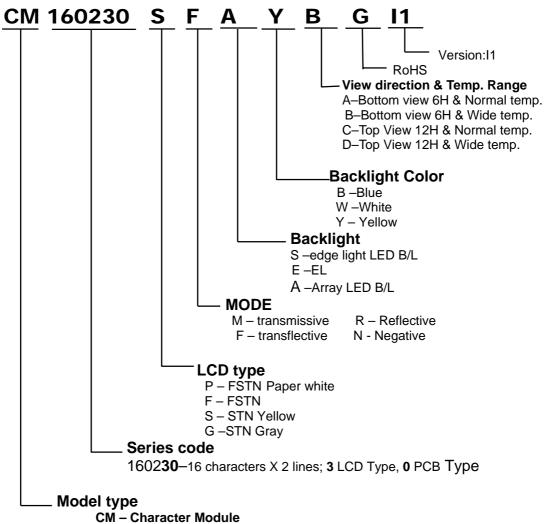
Inspection level: Level II



LOT NUMBERING SYSTEM



LCM NUMBERING SYSTEM 13.



GM - Graphic Module

DATA IMAGE

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14. PRECAUTION FOR USING LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

- (1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.
- (2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface, wipe gently with cotton, chamois or other soft material soaked in petroleum benzin.
- (3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.
- (4). Glass can be easily chipped or cracked from rough handling, especially at corners and edges.
- (5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

- (1). Do not tamper in any way with the tabs on the metal frame.
- (2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattern.
- (3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).
- (4). When mounting a LCM make sure that the PCB is not under any stress such as bending or twisting . Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- (5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

- (1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body
- (2). The modules should be kept in antistatic bags or other containers resistant to static for storage.
- (3). Only properly grounded soldering irons should be used
- (4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

- (5) The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
- (6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3 Soldering

- (1). Solder only to the I/O terminals.
- (2). Use only soldering irons with proper grounding and no leakage.
- (3). Soldering temperature : $280^{\circ}\text{C} \pm 10^{\circ}\text{C}$
- (4). Soldering time: 3 to 4 sec.
- (5). Use eutectic solder with resin flux fill.
- (6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4 Operation

- (1). The viewing angle can be adjusted by varying the LCD driving voltage V0.
- (2). Driving voltage should be kept within specified range; excess voltage shortens display life.
- (3). Response time increases with decrease in temperature.
- (4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- (5). Mechanical disturbance during operation (such as pressing on the viewing area) may cause the segments to appear "fractured".

2.5 Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6 Limited Warranty

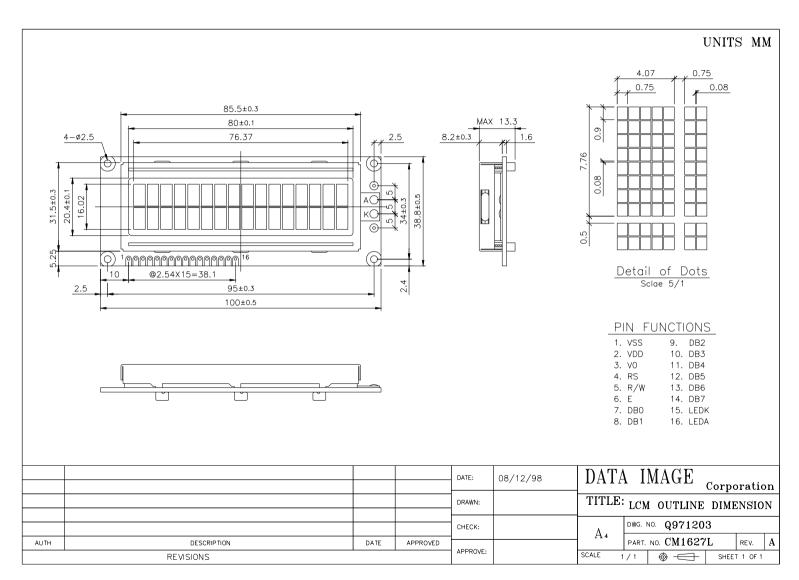
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Unless otherwise agreed between DATA IMAGE and customer, DATA IMAGE will replace or repair any of its LCD and LCM which is found to be defective electrically and visually when inspected in accordance with DATA IMAGE acceptance standards, for a period on one year from date of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of DATA IMAGE is limited to repair and/or replacement on the terms set forth above. DATA IMAGE will not responsible for any subsequent or consequential events.



Confidential Document 15. OUTLINE DRAWING





16. PACKAGE INFORMATION

